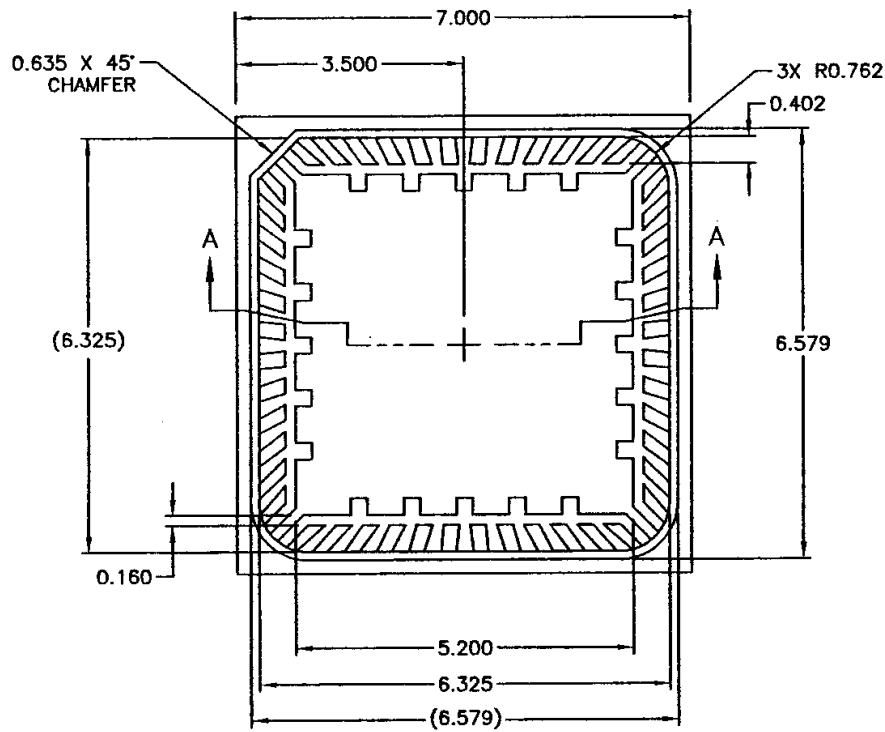
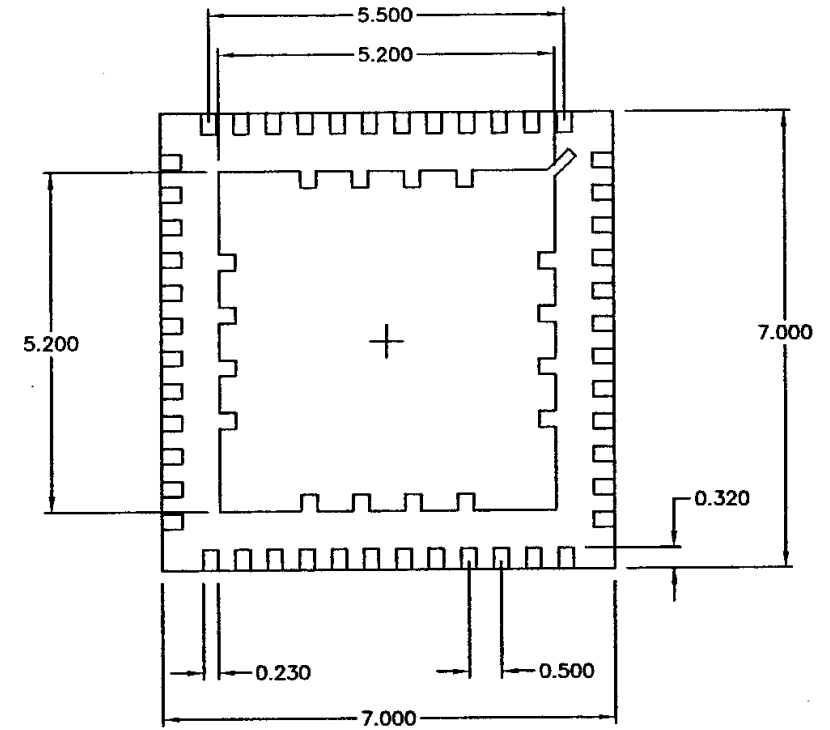
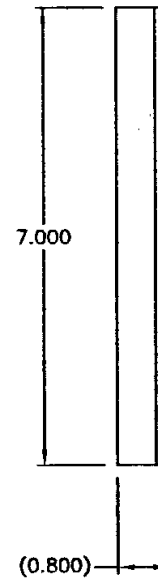


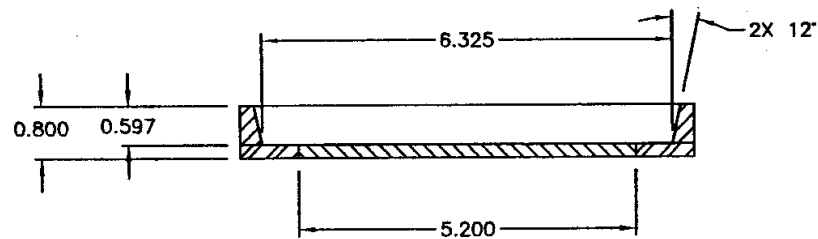
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEAD FRAME: COPPER, FH 194.
3. LEAD FINISH: FULL GOLD PLATE.
4. LEAD THICKNESS: 0.2030 ± 0.0076.
5. FRAME THICKNESS: 0.2030 ± 0.0076.
6. DIE PAD: 5.200 X 5.200.
7. JEDEC OUTLINE: MO-220 (VKKD).

	THIRD ANGLE PROJECTION	DRAWN BY	DATE
		APP BY	DATE
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XX ± 0.15    X.XXX ± --- X.XXX ± 0.100    ANGLES: ± 1°		CUSTOMER	
DO NOT SCALE DRAWING			

48 Lead 7mm x 7mm

QFN7X7-048 REV 2